

MSF4N60

MSF4N60 600V N-Channel MOSFET

Description

The MSF4N60 is a N-channel enhancement-mode MOSFET , providing the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness. The TO-220F package is universally preferred for all commercial-industrial applications

Features

- Low On Resistance
- Simple Drive Requirement
- Low Gate Charge
- Fast Switching Characteristic
- RoHS compliant package

Application (500V-600V)

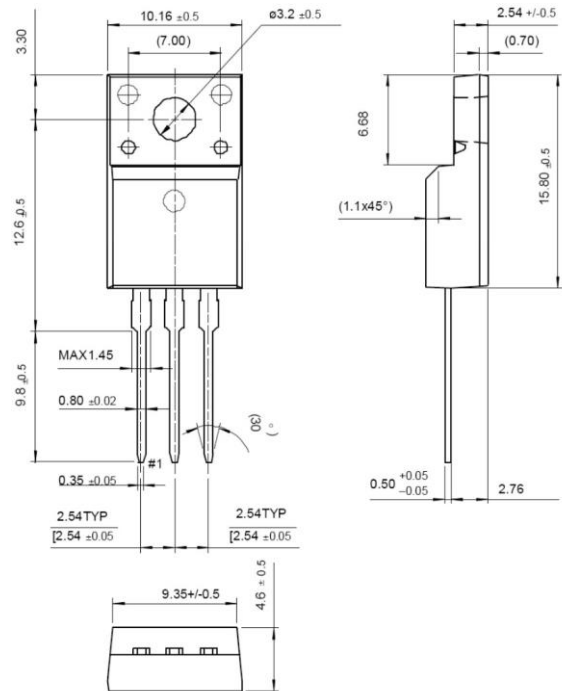
- Open Framed Power Supply
- Adapter
- STB

Packing & Order Information

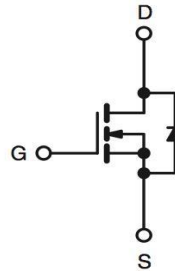
50/Tube ; 1,000/Box



**RoHS
COMPLIANT**



Graphic symbol



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V _{DSS}	Drain-Source Voltage	600	V
V _{GS}	Gate-Source Voltage	±30	V
I _D	Drain Current -Continuous (TC=25°C)	4.5	A
	Drain Current -Continuous (TC=100°C)	2.6	A
I _{DM}	Drain Current Pulsed	18	A
I _{AR}	Avalanche Current	4.0	A
E _{AS}	Single Pulsed Avalanche Energy	33	mJ
E _{AR}	Repetitive Avalanche Energy	10	mJ
dv/dt	Peak Diode Recovery dv/dt	4.5	V/ns
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C

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Absolute Maximum Ratings

TPKG	Maximum Temperature for Soldering @ Package Body for 10 seconds	260	°C
P _D	Total Power Dissipation (TC=25°C)	31	W
	Derating Factor above 25 °C	0.25	W/°C
T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C
T _J	Storage Temperature	150	°C

Notes;

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. I_{AS}=4A, V_{DD}=50V, L=8mH, V_G=10V, Starting T_J=25°C
3. I_{SD}≤4A, di/dt≤100A/μs, V_{DD}≤BV_{DSS}, Starting T_J=25°C

Thermal Characteristics (Tc=25°C unless otherwise noted)

Symbol	Parameter	Max.	Units
R _{θJC}	Thermal Resistance, Junction-to-Case	3.7	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	62.5	

Static Characteristics

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V , I _D = 250μA	600	--	--	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C	--	0.6	--	V/°C
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2.0	--	4.0	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 600 V , V _{GS} = 0 V V _{DS} = 480 V , T _C = 125°C	--	--	1 10	μA
I _{GSS}	Gate-Body Leakage Forward	V _{GS} = ±30	--	--	±100	nA
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 2.25 A	--	2.0	2.5	Ω

Dynamic Characteristics

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
t _{d(on)}	Turn-On Time	V _{DS} = 300 V, I _D = 4.5 A, R _G = 25 Ω , V _{GS} = 10 V	--	10	30	ns
t _r	Turn-On Time		--	40	80	ns
t _{d(off)}	Turn-Off Delay Time		--	40	100	ns
t _f	Turn-Off Fall Time		--	50	90	ns
Q _g	Total Gate Charge	V _{DS} = 480 V, I _D = 4.5 A, V _{GS} = 10 V	--	16	--	nC
Q _{gs}	Gate-Source Charge		--	2.5	--	nC
Q _{gd}	Gate-Drain Charge		--	6.5	--	nC

MSF4N60

MSF4N60 600V N-Channel MOSFET

Dynamic Characteristics

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
C_{ISS}	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	560	--	pF
C_{OSS}	Output Capacitance		--	55	--	pF
C_{RSS}	Reverse Transfer Capacitance		--	7	--	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
I_S		$V_D = V_G = 0$	--	--	4.0	A
I_{SM}			--	--	16	
V_{SD}		$I_S = 3\text{ A}, V_{GS} = 0\text{ V}$	--	--	1.4	V
t_{rr}		$I_S = 3\text{ A}, V_{GS} = 0\text{ V}$ $diF/dt = 100\text{ A}/\mu\text{s}$	--	270	--	ns
Q_{rr}			--	18	--	μC

Notes;

1. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$

MSF4N60

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■ Characteristics Curve

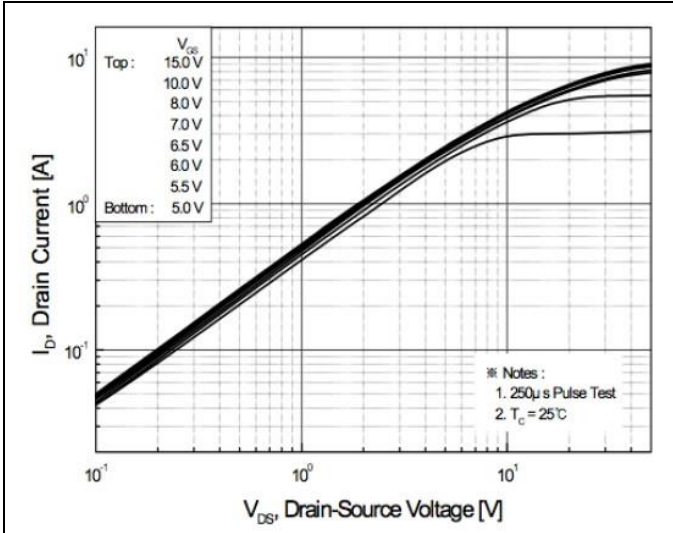


FIG.1-ON REGION CHARACTERISTICS

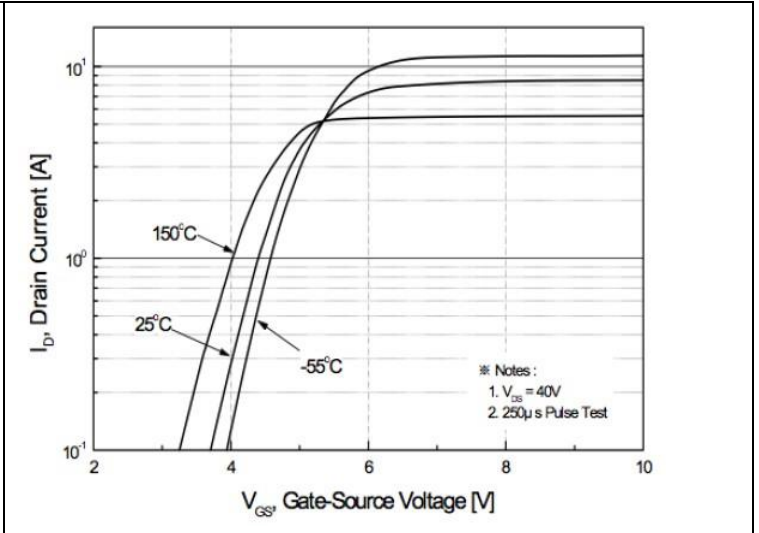


FIG.2-TRANSFER CHARACTERISTICS

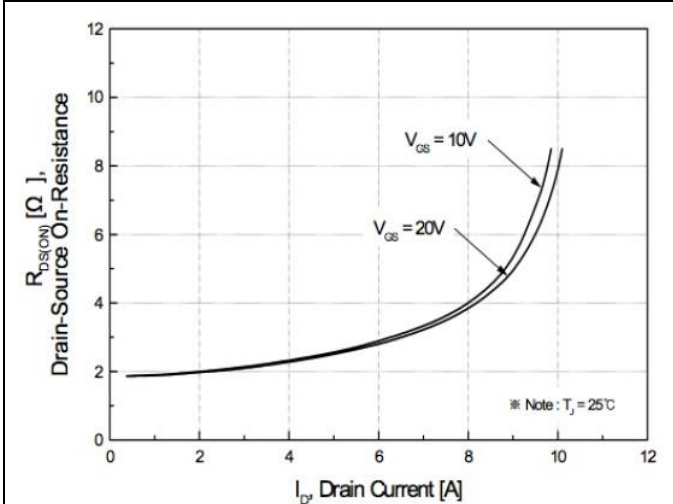


FIG.3-ON RESISTANCE VARIATION VS DRAIN CURRENT AND GATE VOLTAGE

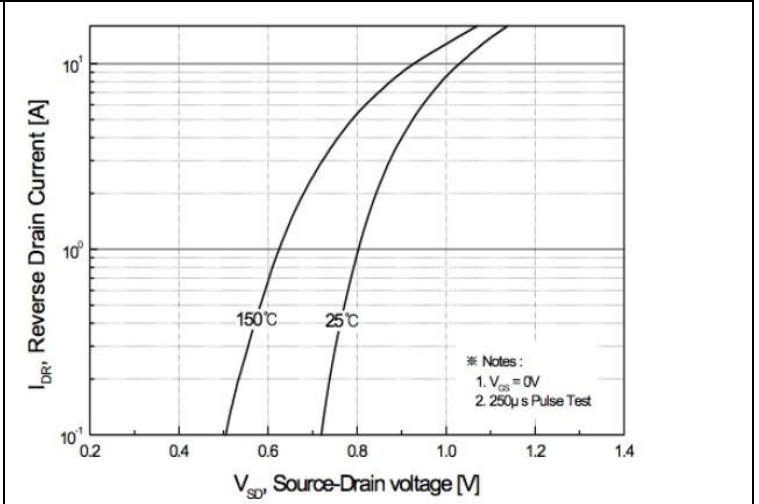


FIG.4-BODY DIODE FORWARD VOLTAGE VARIATION WITH SOURCE CURRENT AND TEMPERATURE

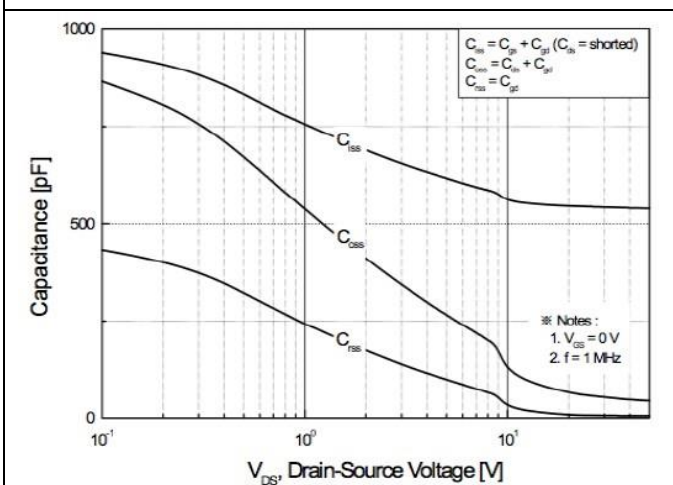


FIG.5-CAPACITANCE CHARACTERISTICS

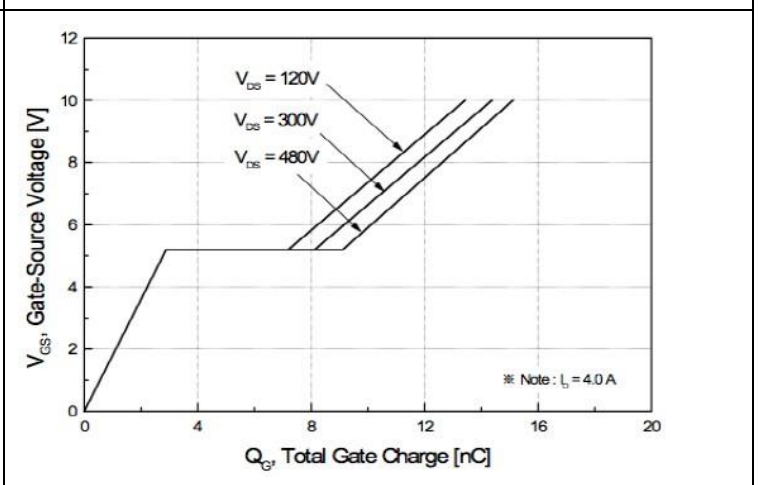


FIG.6-GATE CHARGE CHARACTERISTICS

MSF4N60

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■ Characteristics Curve

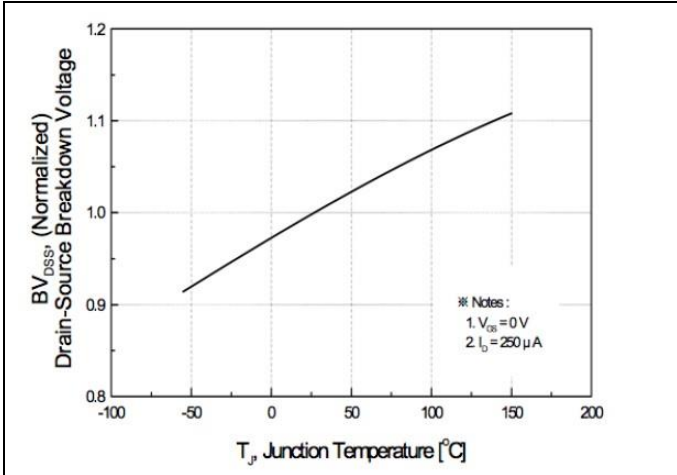


FIG.7-BREAKDOWN VOLTAGE VARIATION VS TEMPERATURE

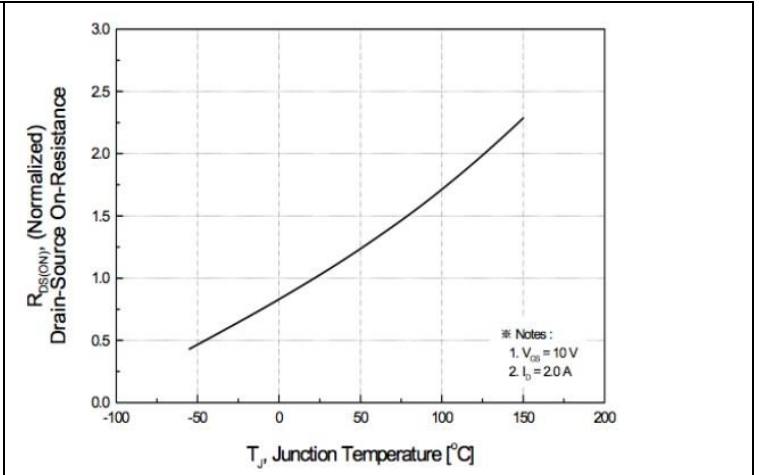


FIG.8-ON-RESISTANCE VARIATION VS TEMPERATURE

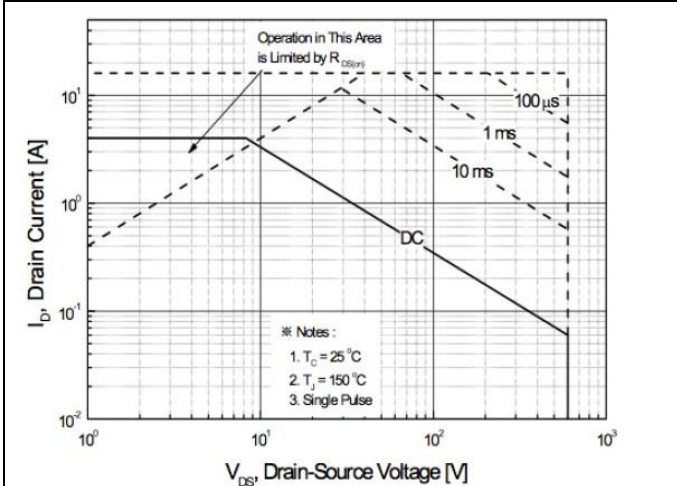


FIG.9-MAXIMUM SAFE OPERATING AREA

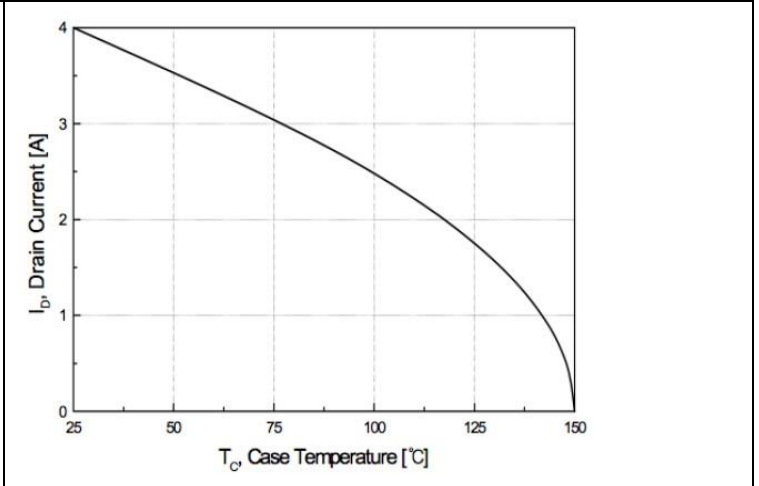


FIG.10-MAXIMUM DRAIN CURRENT VS CASE TEMPERATURE

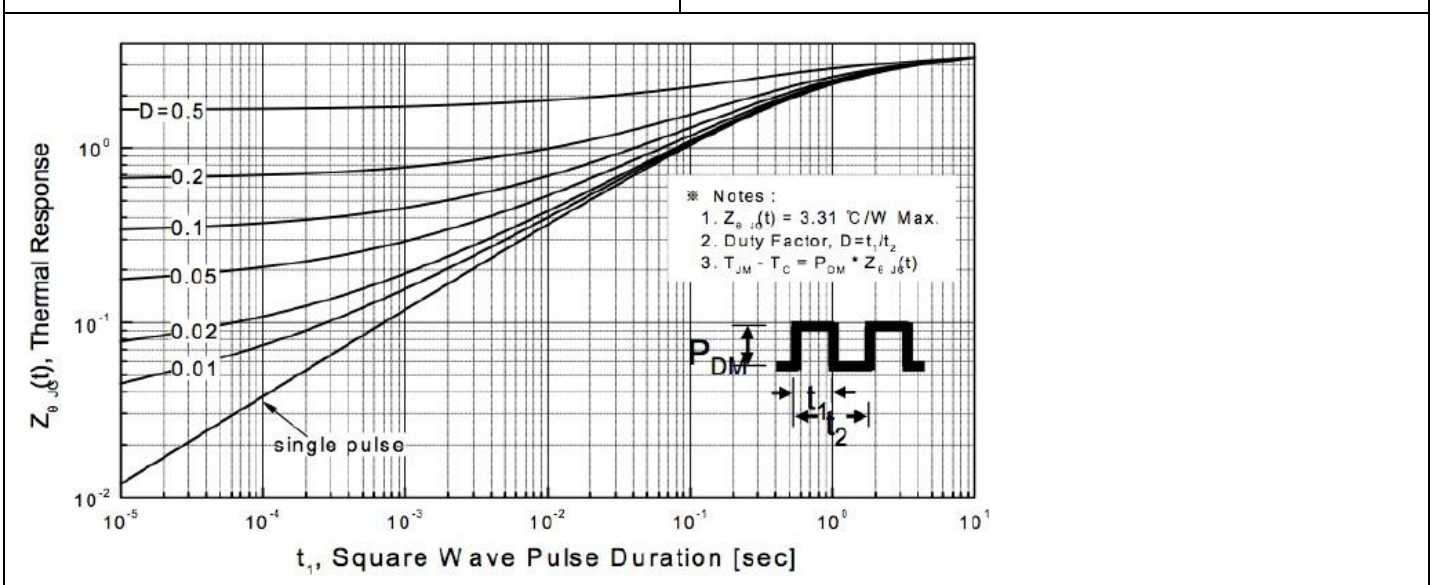


FIG.11-TRANSIENT THERMAL RESPONSE CURVE

MSF4N60

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■ Characteristics Test Circuit & Waveform

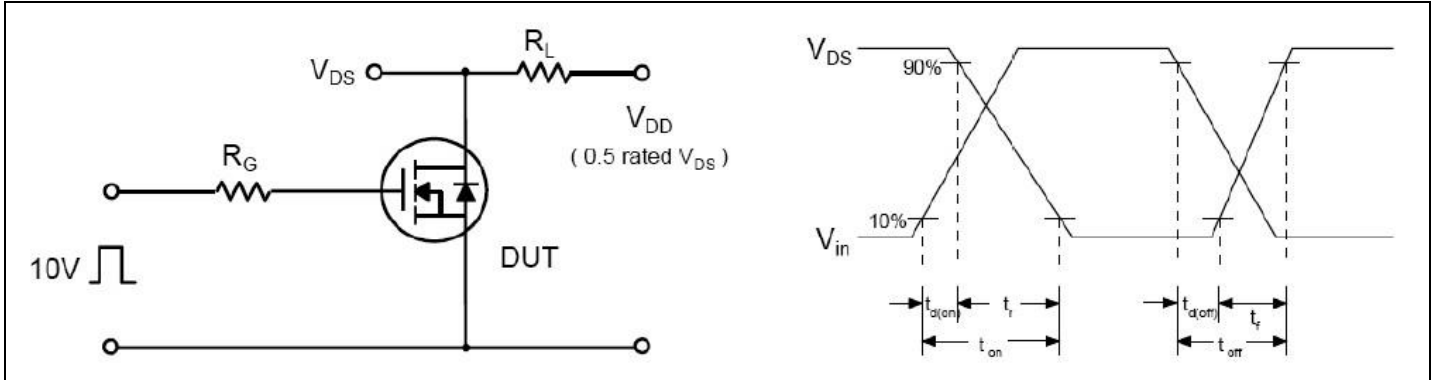


Fig 12. Resistive Switching Test Circuit & Waveforms

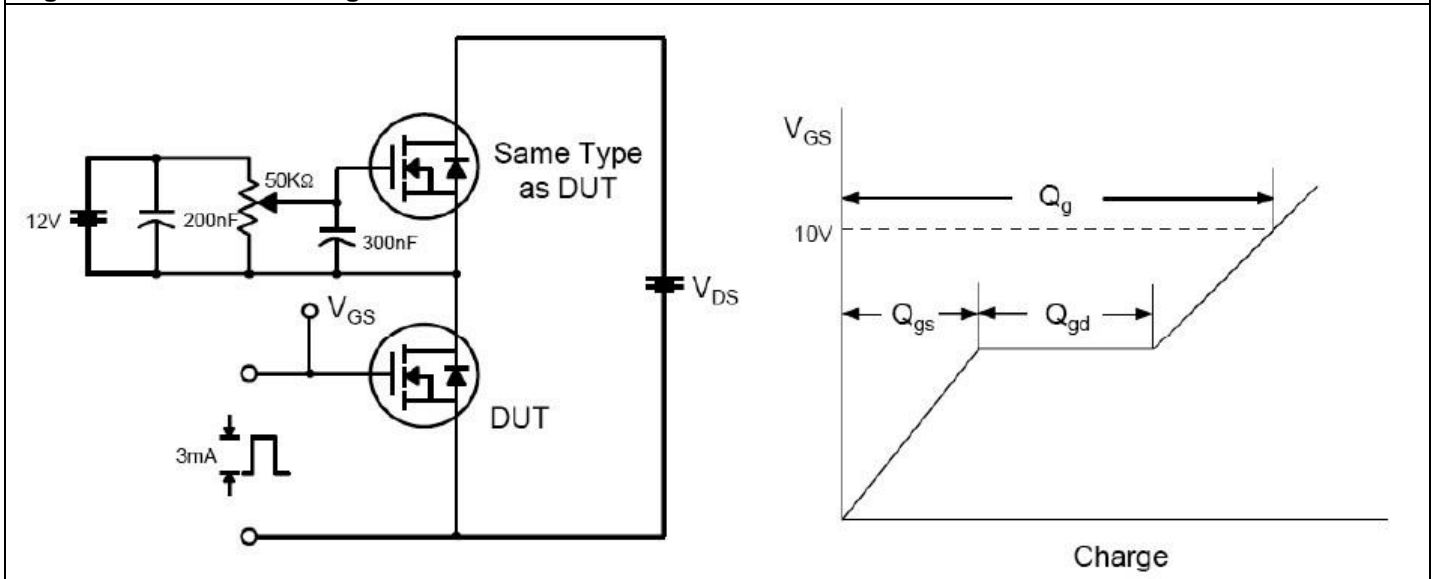


Fig 13. Gate Charge Test Circuit & Waveform

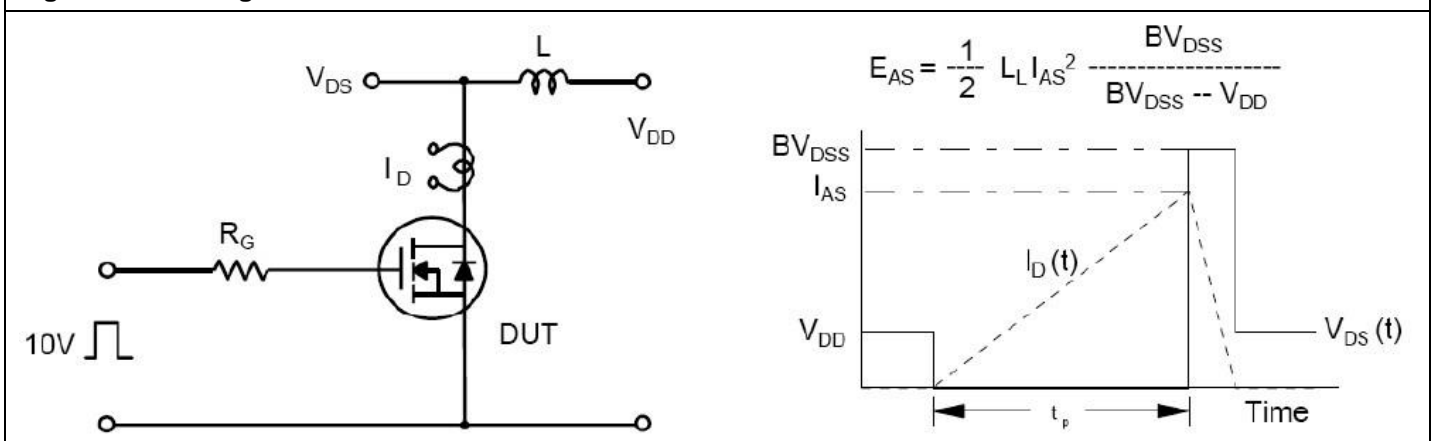


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

MSF4N60

MSF4N60 600V N-Channel MOSFET

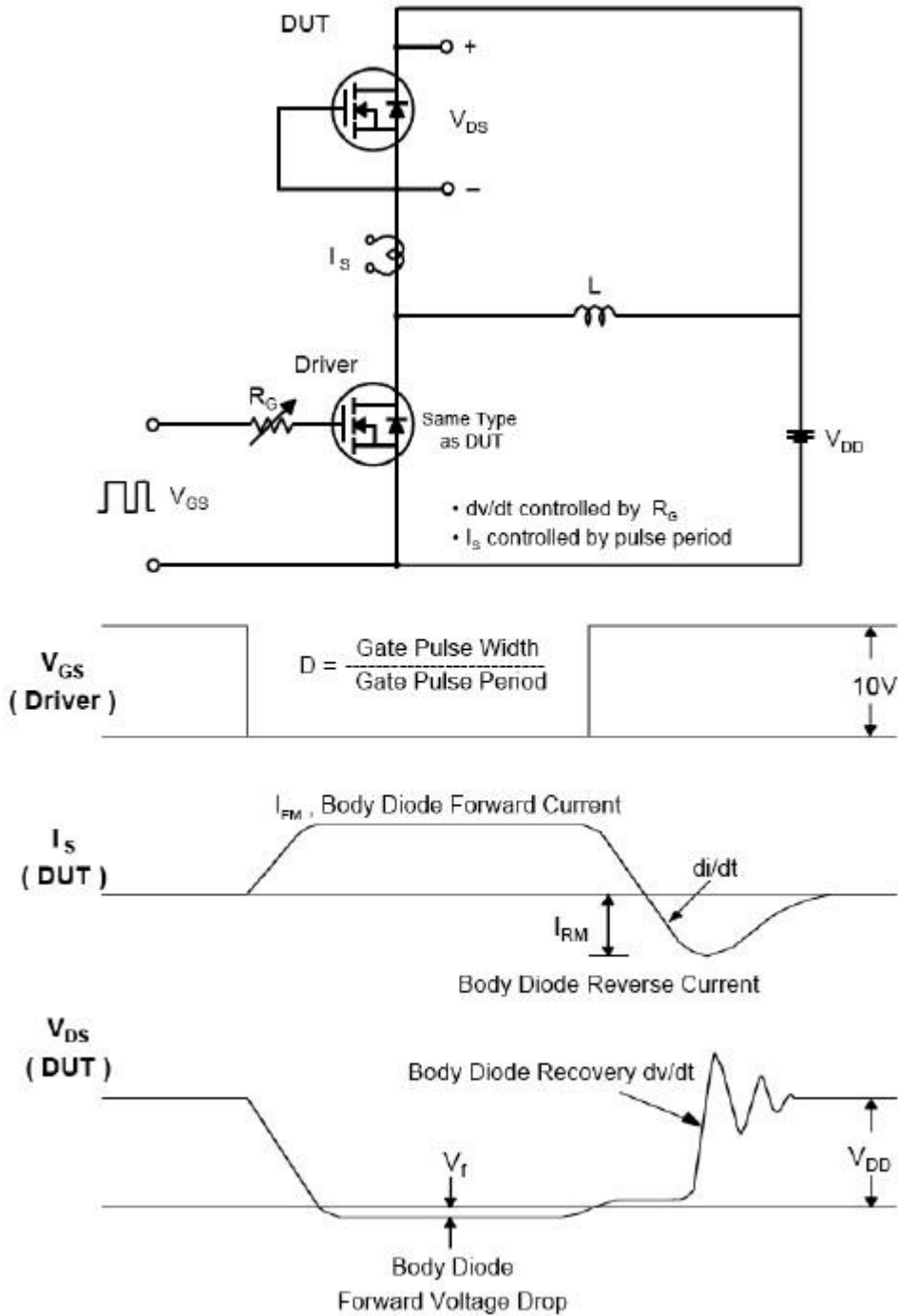


Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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